Prisemi® PB15302

USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator

Description

The PB15302 is a switch-mode charging IC with maximum 2.2A current for lithium battery and lithium polymer battery. The IC has 5V, 1A OTG function and I2C function. The charging parameter such as charging current, full charging voltage and input current can be precisely configured by I2C function. The package type is DFN(3.0mm x 3.0mm) with 12 pins.

The PB15302 is designed with standard four-stage charging process: active, pre-charging, constant current, constant voltage and perfect protection mechanism for over current, over voltage, under voltage and over temperature. It is integrated with synchronous PWM control, high power MOSFET, and high voltage OVP circuits. The PB15302 has high charging efficiency (94%), low internal resistance (45mΩ), and high DC withstand voltage (29V).

Feature

- Fully Integrated, High-Efficiency Charger for Single-Cell Li-Ion and Li-Polymer Battery Packs
- Charge Voltage Accuracy: ±0.5% 25℃
- ±5% Charge Current Regulation Accuracy
- 29V Absolute Maximum Input Voltage
- 6V Maximum Input Operating Voltage
- 2.2A Maximum Charge Rate
- 5V, 700mA Boost Mode for USB OTG for 3.0 to 4.5V Battery Input
- 3.0 mm x 3.0mm 12-Pin DFN Package
- Programmable through I^2C Interface:
  -Input Current
  -Fast-Charge/Termination Current
  -Charger Voltage
  -Termination Enable
- Synchronous Buck PWM Controller with Wide Duty Cycle Range
- Small Footprint 1μH External Inductor
- Perfect protection mechanism:
  -OVP, OCP, OTP

Application

- Cellular Phones, Smart Phones, PDAs
- Tablet, Portable Media Players
- Gaming Device, Digital Cameras

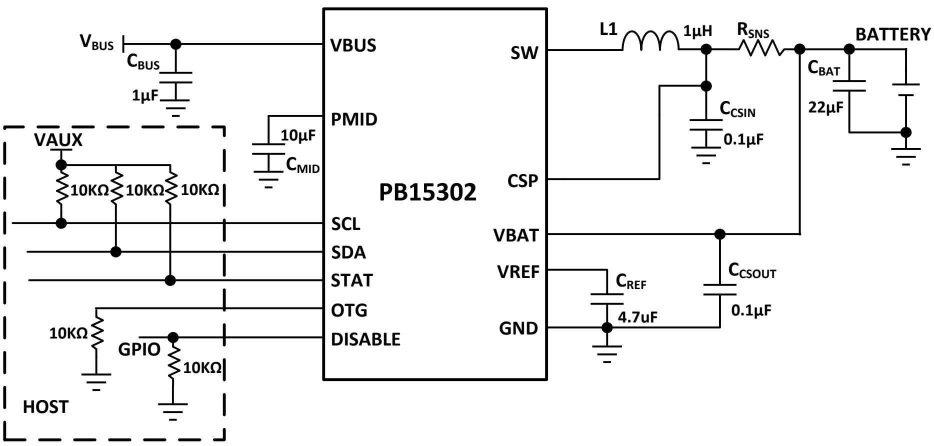


Figure 1: Typical Application

Recommended External Components

Key Components	Recommended specification
L1	Inductor, 1.0-2.2uH, +-20%, Isat>3A
C_{MID}	Capacitor, 10-22μF, +-10%, Rated Voltage >10V
C_{REF}	Capacitor, 2.2μF, +-10%, Rated Voltage >10V, 0402 or Capacitor, 4.7μF, +-10%, Rated Voltage >6V, 0402
C_{BUS}	Capacitor, 1μF, +-10%, Rated Voltage >25V

Block Diagram

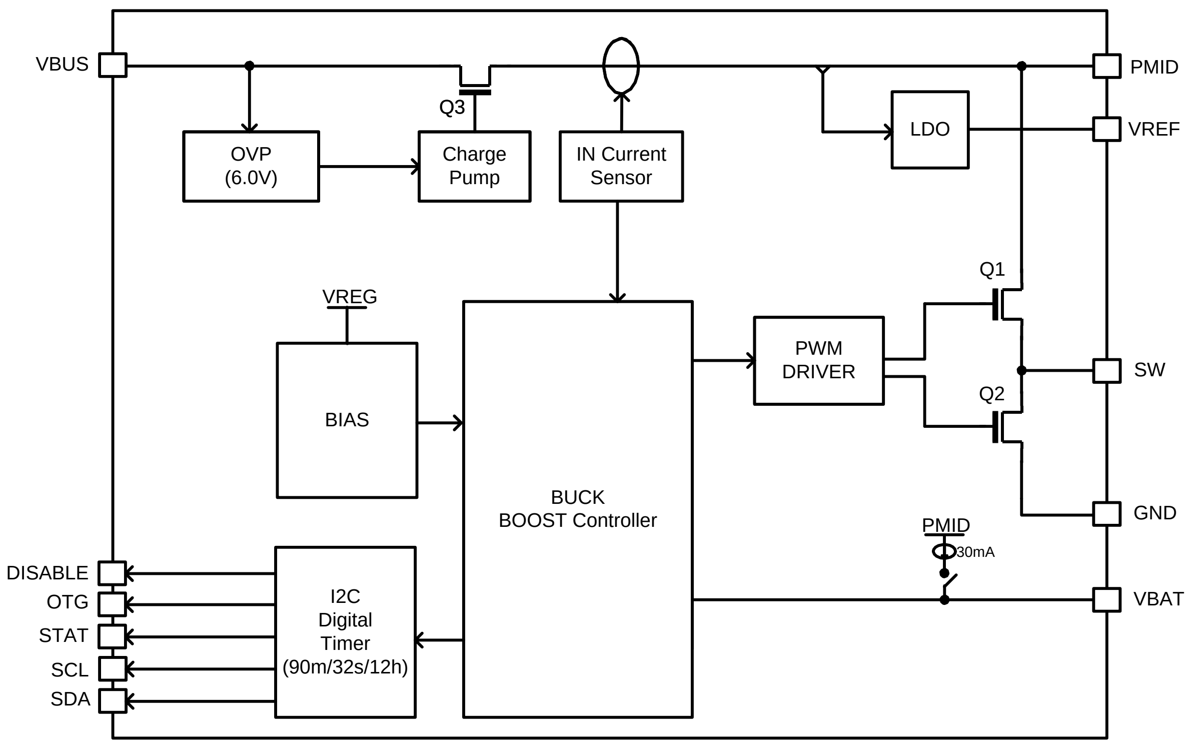


Figure 2: IC and System Block Diagram

Pin Configuration

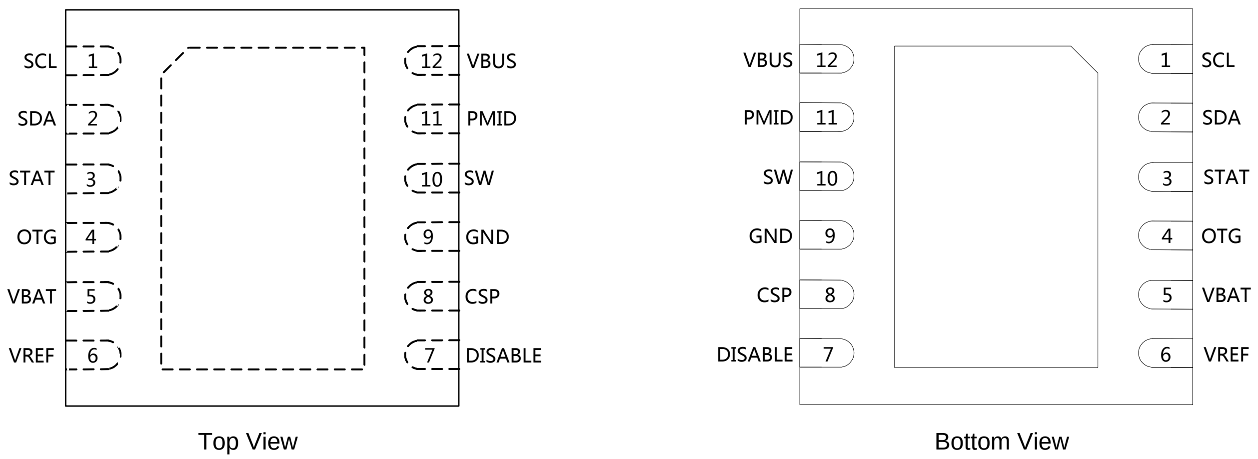


Figure 3: DFN3.0 x3.0-12L Pin Assignments

Pin Definitions

Pin#	Name	Description
1	SCL	**I²C Interface Serial Clock.** This pin should not be left floating.
2	SDA	**I²C Interface Serial Data.** This pin should not be left floating.
3	STAT	**Status.** Open-drain output indicating charge status. The IC pulls this pin LOW when charge is in process.
4	OTG	**On-The-Go.** Enables boost regulator in conjunction with OTG_EN and OTG_PL bits.
5	VBAT	**Battery Voltage.** Connect to the positive (+) terminal of the battery pack. Bypass with a 0.1μF capacitor to GND if the battery is connected through long leads.
6	VREF	**Bias voltage.** Connect to a **4.7uF** capacitor to GND. The output voltage is PMID, which is limited to 6.5V. Any resistor loading to VREF is **NOT** recommended.
7	DISABLE	**Charge Disable.** If this pin is "1", charging is disabled. When LOW, charging is controlled by I2C registers.
8	CSP	**Current-Sense Input.** Connect to the sense resistor in series with the battery. The IC uses this node to sense current into the battery. Bypass this pin with a 0.1μF capacitor to GND.
9	GND	**Power Ground.** Power return for gate drive and power transistors. The connection from this pin to the bottom of C_{MID} should be as short as possible.
10	SW	**Switching Node.** Connect to output inductor.
11	PMID	**Power Input Voltage.** Power input to the charger regulator, bypass point for the input current sense, and high-voltage input switch. Bypass with a minimum of 10μF, 10V capacitor to GND.
12	VBUS	**Charger Input Voltage** and USB-OTG output voltage. Bypass with 1μF capacitor to GND.

Maximum Ratings and Thermal Characteristics(T_A=25℃ unless otherwise noted)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Recommended Operating Conditions

Parameter		Symbol	Min.	Max.	Units
VBUS Voltage	Continuous	V_{BUS}	-0.7	29.0	V
	Pulsed,100ms Maximum Non-Repetitive		-1.0		
STAT Voltage		V_{STAT}	-0.3	7.0	V
PMID Voltage		V_I		7.0	V
SW,CSP,VBAT,VREF, DISABLE Voltage			-0.3	7.0	
Voltage on Other Pins		V_O	-0.3	6.5	V
Maximum VBUS Slope above 5.5V when Boost or Charger are Active		$\frac{dV_{BUS}}{dt}$		4	V/μs
Electrostatic Discharge Protection Level	Human Body Model per JESD22-A114	ESD	2000		V
	Charged Device Model per JESD22-C101		500		
Junction Temperature		T_J	-40	+150	℃
Storage Temperature		T_{STG}	-65	+150	℃
Lead Soldering Temperature, 10 Seconds		T_L		+260	℃

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Prisemi does not recommend exceeding them or designing to absolute maximum ratings.

Parameter		Symbol	Min.	Max.	Units
Supply Voltage		V_{BUS}	4.5	6	V
Maximum Battery Voltage when Boost enabled		$V_{BAT(MAX)}$		4.5	V
Negative VBUS Slew Rate during VBUS Short Circuit, C_{MID}≤ 22μF, see VBUS Short While Charging	T_A≤60℃	$-\frac{dV_{BUS}}{dt}$		4	V/μs
	T_A≥60℃			2	
Ambient Temperature		T_A	-30	+85	℃
Junction Temperature (see Thermal Protection section)		T_J	-30	+140	℃

Thermal Properties

Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with four-layer 2s2p boards in accordance to JEDEC standard JESD51. Special attention must be paid not to exceed junction temperature $T_{J(max)}$ at a given ambient temperature T_A.

Parameter	Symbol	Typical	Units
Junction-to-Ambient Thermal Resistance	θ_{JA}	60	℃/W
Junction-to-PCB Thermal Resistance	θ_{JB}	20	℃/W

Electrical characteristics per line@25℃(unless otherwise specified)

Unless otherwise specified: according to the circuit of Figure 1; recommended operating temperature range for T_J and T_A; V_{BUS}=5.0V; HZ_MODE; OPA_MODE=0; (Charge Mode); SCL, SDA, OTG=0 or 1.8V; and typical values are for T_J=25℃.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Power Supplies						
VBUS Current	I_{VBUS}	V_{BUS}>$V_{BUS(MIN)}$, PWM Switching		1.5	10	mA
		V_{BUS}>$V_{BUS(MIN)}$; PWM Enabled, Not Switching (Battery OVP Condition); I_IN Setting=100mA		1.2	10	mA
VBAT to VBUS Leakage Current	I_{LKG}	0℃<T_J<85℃ V_{BAT}=4.2V,V_{BUS}=0V		0.2	1	μA
Battery Discharge Current in High-Impedance Mode	I_{BAT}	0℃<T_J<85℃ V_{BAT}=4.2V		5	10	μA
Charger Voltage Regulation						
Charge Voltage Range	V_{OREG}		4.1		4.40	V
Charge Voltage Accuracy		T_J=25℃	-0.5%		+0.5%	
		T_J=0~125℃	-1%		1%	
Charging Current Regulation						
Output Charge Current Range	I_{OCHRG}	V_{LOWV} < V_{BAT} < V_{OREG} V_{BUS} > V_{SLP}, R_{SENSE}=56mΩ	595		1750	mA
Charge Current Accuracy Across R_{SENSE}		VBAT=3.8V	95	100	105	%

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Logic Levels: DISABLE, SDA, SCL, OTG						
High-Level Input Voltage	V_{IH}		1.2			V
Low-Level Input Voltage	V_{IL}				0.4	V
Input Bias Current	I_{IN}	Input Tied to GND or V_{IN}		0.01	1.00	mA
Charge Termination Detection						
Termination Current Range	$I_{(TERM)}$	$V_{BAT} > V_{OREG} - V_{RCH}$ $V_{BUS} > V_{SLP}$	69		230	mA
Wake-up voltage						
Wake-up voltage Range	V_{wakeup}	Soft start current if vbat is lower than V_{wakeup} (Rsense=56mΩ)	3.0	3.15	3.3	V
Wake-up current	I_{wakeup}			352		mA
Input Power Source Detection						
VBUS Input Voltage Rising	$V_{IN(MIN)1}$	To Initiate and Pass VBUS Validation		4.29	4.42	V
Minimum VBUS during Charge	$V_{IN(MIN)2}$	During Charging		4.1	4.15	V
VBUS Validation Time	t_{VBUS_VALID}			25		ms
Special Charger (V_{BUS})						
Special Charger Set point	V_{SP}	VSP[2:0]=100		4.52		V
Special Charger Set point			-3		+3	%
Input Current Limit						
Input Current Limit Threshold	I_{INLIM}	I_{IN} Set to 500mA		480	510	mA

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Battery Recharge Threshold						
Recharge Threshold	V_{RCH}	Below $V_{(OREG)}$		140	200	mV
STAT Output						
STAT Output Low	$V_{STAT(OL)}$	I_{STAT}=10mA			0.4	V
STAT High Leakage Current	$I_{STAT(OH)}$	V_{STAT}=5V			1	μA
Sleep Comparator						
Sleep-Mode Entry Threshold, $V_{BUS} - V_{BAT}$	V_{SLP}	V_{BUS} Falling		0.25		V
Power Switches (see Figure 2)						
Q3 On Resistance (VBUS to PMID)	$R_{DS(ON)}$	$I_{IN(LIMIT)}$=500mA		40	60	mΩ
Q1 On Resistance (PMID to SW)				50	75	
Q2 On Resistance (SW to GND)				55	80	
Charger PWM Modulator						
Oscillator Frequency	f_{SW1}		1.25	1.5	1.65	MHz
	f_{SW2}		1.65	2.0	2.3	
Maximum Duty Cycle	D_{MAX}				97	%
Minimum Duty Cycle	D_{MIN}			0		%
Boost Mode Operation (OPA_MODE=1, HZ_MODE=0)						
Boost Output Voltage at VBUS	V_{BOOST}	3.3V<V_{BAT}<4.5V, I_{LOAD} from 0 to 500mA	4.75	5.05	5.3	V
Boost Mode Quiescent Current	$I_{BAT(BOOST}$	PFM Mode, V_{BAT}=3.6V, I_{OUT}=0		1.6	10	mA
Minimum Battery Voltage for Boost Operation	$UVLO_{BST}$			3.0		V

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
VBUS Load Resistance						
VBUS to GND Resistance	R_{VBUS}	Normal Operation		1500		KΩ
Protection and Timers						
VBUS Over-Voltage Shutdown	$VBUS_{OVP}$	V_{BUS} Rising	5.75	5.9	6.05	V
Hysteresis		V_{BUS} Falling		150		mV
Battery Short-Circuit Threshold	V_{SHORT}	V_{BAT} Rising	1.9	2.0	2.1	V
Hysteresis		V_{BAT} Falling		0.1		
Linear Charging Current	I_{SHORT}	$V_{BAT} < V_{SHORT}$	20	30	40	mA
Thermal Shutdown Threshold	$T_{SHUTDWN}$	T_J Rising		145		℃
Hysteresis		T_J Falling		10		
12H timer	t_{12H}	Charger Enabled		12		hour
90-Minute Timer	T_{90MIN}	90-Minute Mode		90		min
32-Second Timer	T_{32s}	32-second Mode		32		Sec

I²C Timing Specifications

Guaranteed by design.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
SCL Clock Frequency	f_{SCL}	Standard Mode			100	kHz
		Fast Mode			400	
Bus-Free Time between STOP and START Conditions	t_{BUF}	Standard Mode		4.7		ms
		Fast Mode		1.3		

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
START or Repeated START Hold Time	$t_{HD;STA}$	Standard Mode		4		μs
		Fast Mode		600		ns
SCL LOW Period	t_{LOW}	Standard Mode		4.7		μs
		Fast Mode		1.3		
SCL HIGH Period	t_{HIGH}	Standard Mode		4		μs
		Fast Mode		600		ns
Repeated START Setup Time	$t_{SU;STA}$	Standard Mode		4.7		μs
		Fast Mode		600		ns
Data Setup Time	$t_{SU;DAT}$	Standard Mode		250		ns
		Fast Mode		100		
Data Hold Time	$t_{HD;DAT}$	Standard Mode	0		3.45	μs
		Fast Mode	0		900	ns
SCL Rise Time	t_{RCL}	Standard Mode	$20+0.1C_B$		1000	ns
		Fast Mode	$20+0.1C_B$		300	
SCL Fall Time	t_{FCL}	Standard Mode	$20+0.1C_B$		300	ns
		Fast Mode	$20+0.1C_B$		300	
SDA Rise Time Rise Time of SCL after a Repeated START Condition and after ACK Bit	t_{RDA} t_{RCL1}	Standard Mode	$20+0.1C_B$		1000	ns
		Fast Mode	$20+0.1C_B$		300	

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
SDA Fall Time	t_{FDA}	Standard Mode	$20+0.1C_B$		300	ns
		Fast Mode	$20+0.1C_B$		300	
Stop Condition Setup Time	$t_{SU;STO}$	Standard Mode		4		μs
		Fast Mode		600		ns
Capacitive Load for SDA, SCL	C_B				400	pF

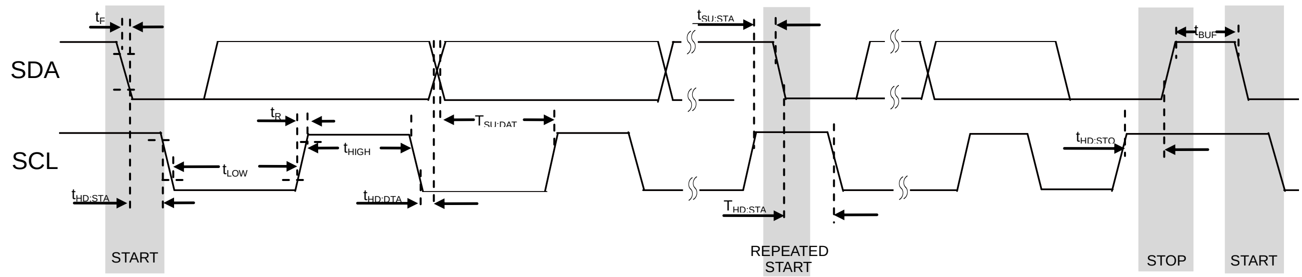


Figure 4. I²C Interface Timing for Fast and Slow Modes

Charge Mode Typical Characteristics

Unless otherwise specified, circuit of Figure 1, V_{OREG}=4.35V, V_{BUS}=5.0V, and T_A=25℃.

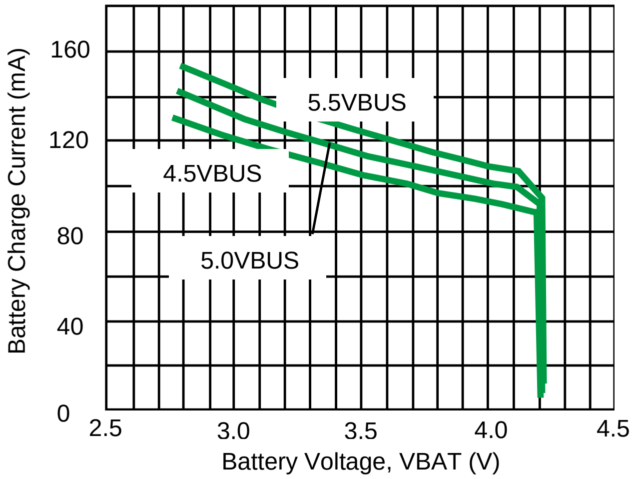


Figure 5. Battery Charge Current vs. V_{BUS} with I_{INLIM}=100mA

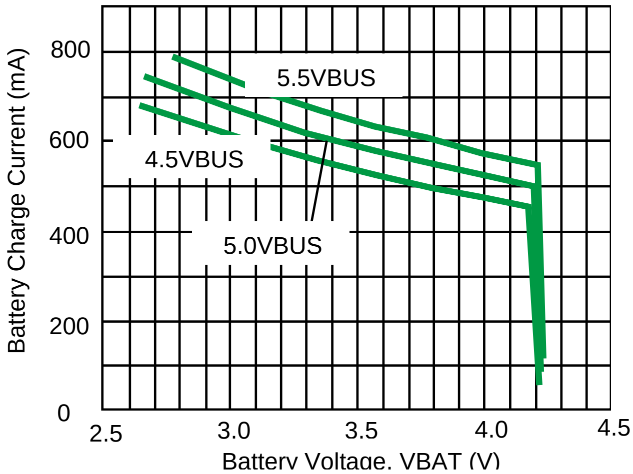


Figure 6. Battery Charge Current vs. V_{BUS} with I_{INLIM}=500mA

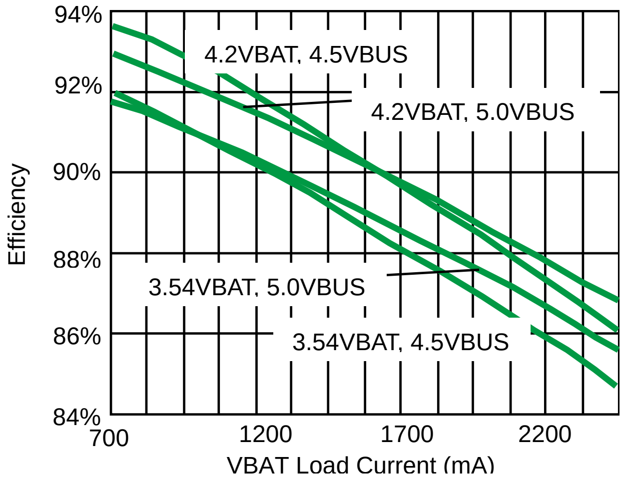


Figure 7. Charger Efficiency, No I_{INLIM}, $I_{OCHARGE}$=2253mA

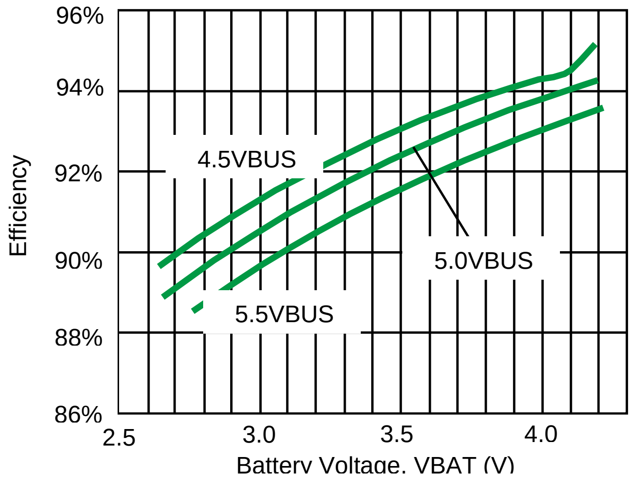


Figure 8. Charger Efficiency vs. V_{BUS}, I_{INLIM}=500mA

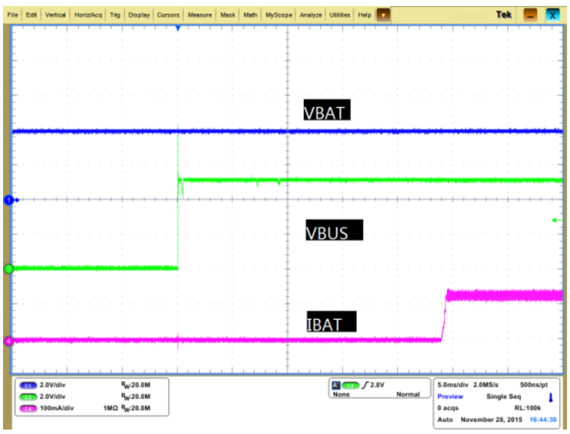


Figure 9. Auto-Charge Startup at V_{BUS} Plug-in, I_{INLIM}=100mA, V_{BAT}=3.9V

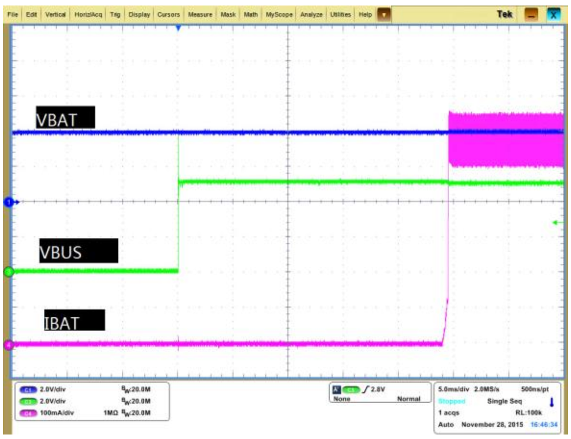


Figure 10. Auto-Charge Startup at V_{BUS} Plug-in, I_{INLIM}=500mA, V_{BAT}=3.9V

Figure 11. Auto-Charge Startup with 300mA Limited Charger/Adaptor, I_{INLIM}=500mA, V_{BAT}=3.9V

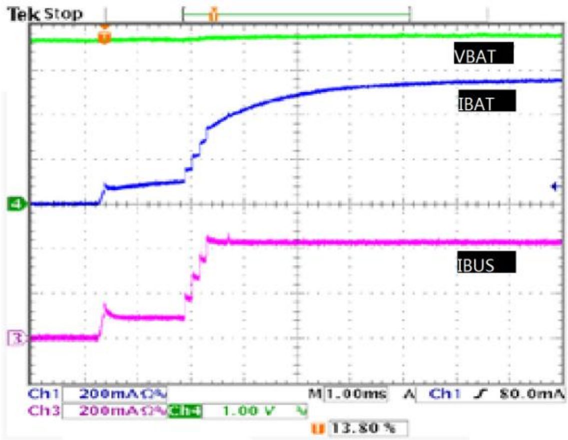


Figure 12. Charger Startup with HZ_MODE Bit Reset, I_{INLIM}=500mA, $I_{OCHARGE}$=956mA, OREG=4.2V, V_{BAT}=3.6V

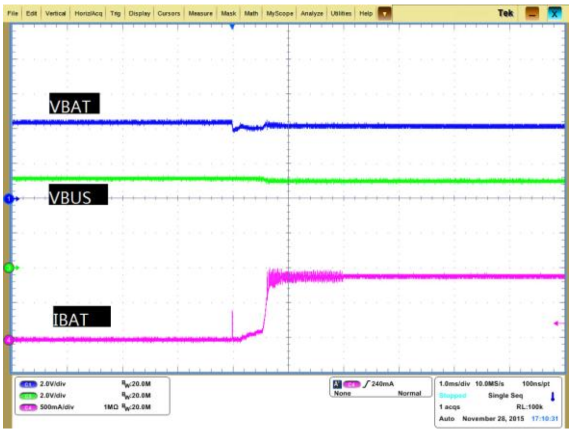


Figure 13. Battery Removal / Insertion during Charging, V_{BAT}=3.9V, $I_{OCHARGE}$=956mA, No I_{INLIM}, TE=0

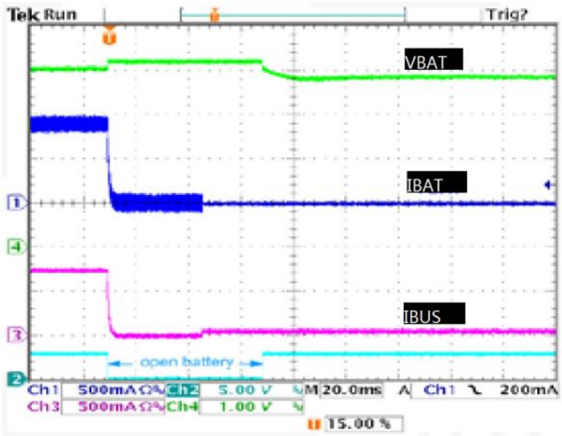


Figure 14. Battery Removal / Insertion during Charging, V_{BAT}=3.9V, $I_{OCHARGE}$=956mA, No I_{INLIM}, TE=1

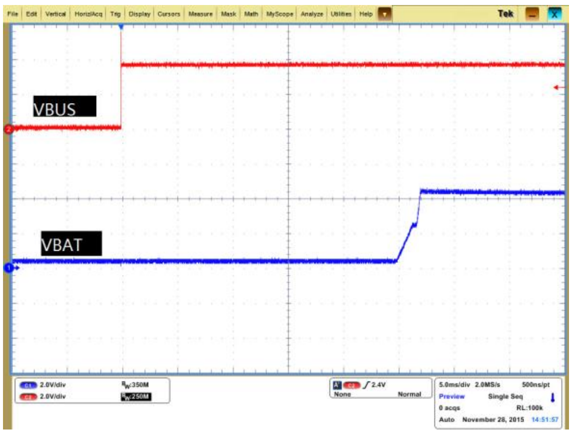


Figure 15. No Battery at V_{BUS} Power-up

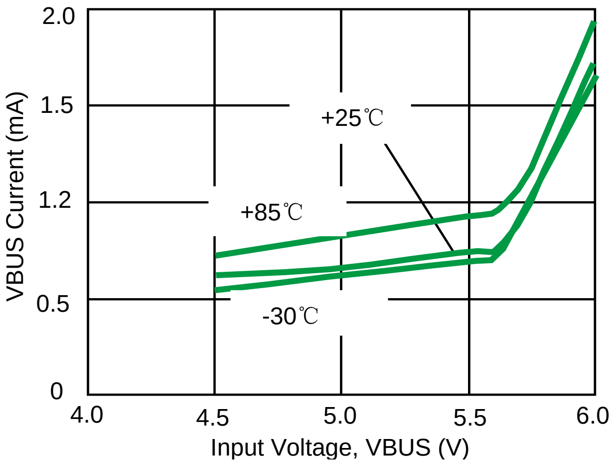


Figure 16. VBUS Current with Battery Open

Boost Mode Typical Characteristics

Unless otherwise specified, using circuit of Figure 1, V_{BAT}=3.6V, T_A=25℃.

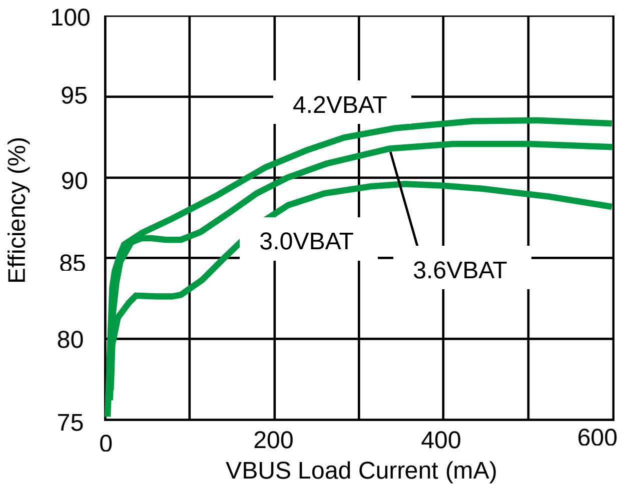


Figure 17. Efficiency vs. VBAT

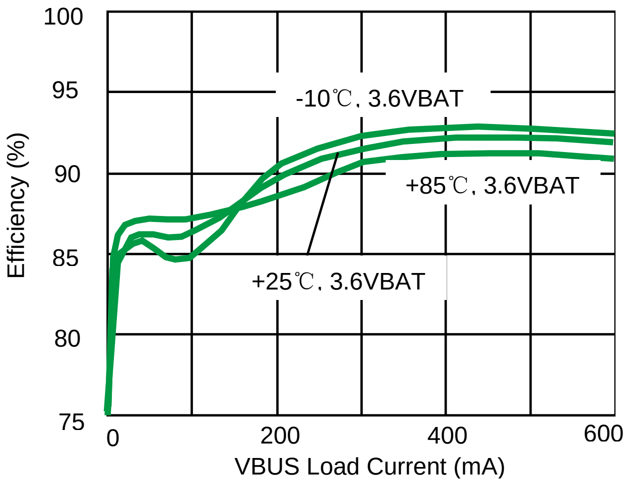


Figure 18. Efficiency Over Temperature

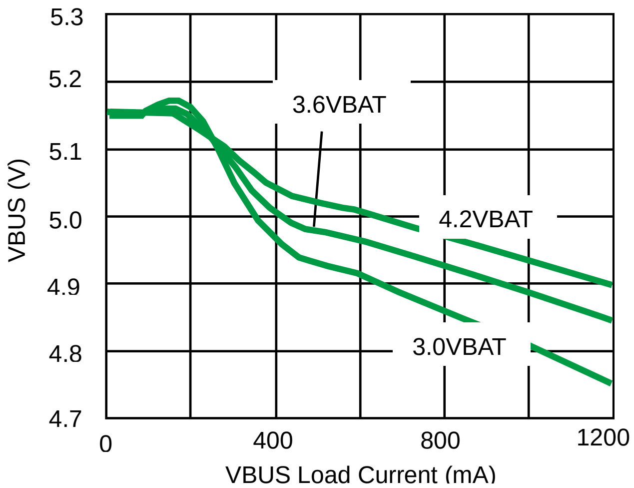


Figure 19. Output Regulation vs. VBAT

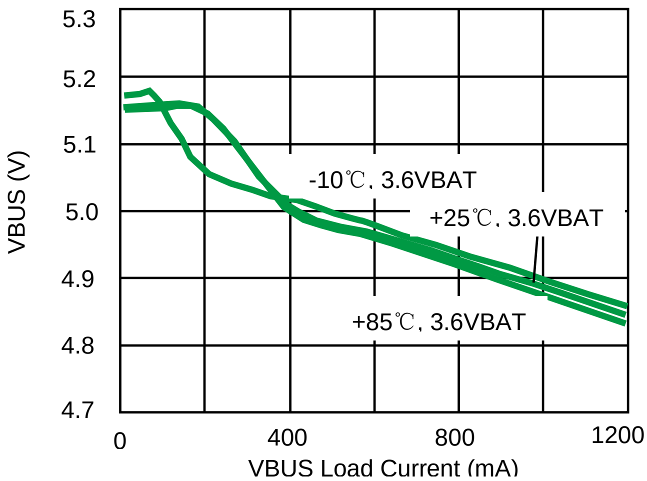


Figure 20. Output Regulation Over Temperature

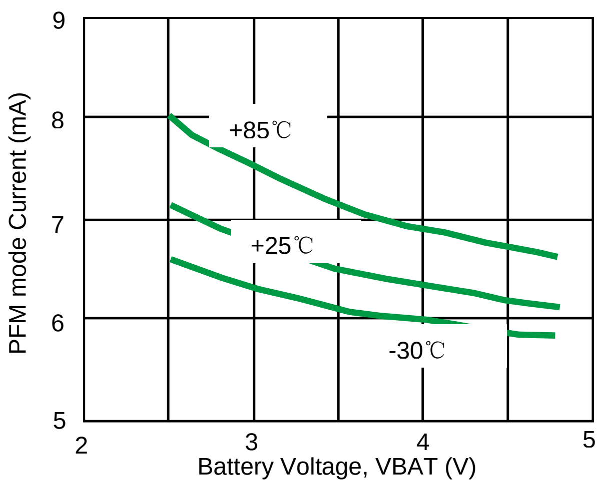


Figure 21. PFM mode Current

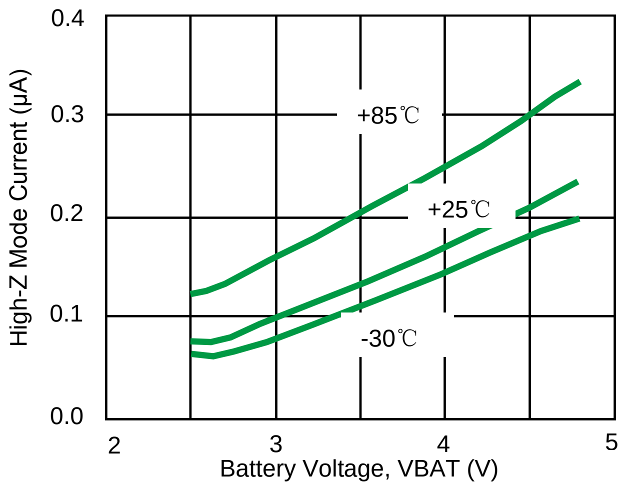


Figure 22. High-Impedance Mode Battery Current

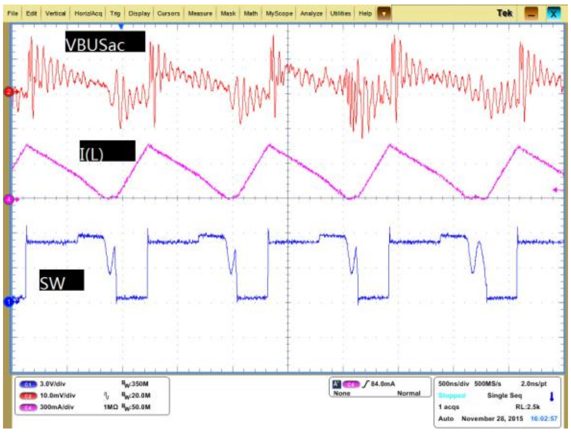


Figure 23. Boost PWM Waveform

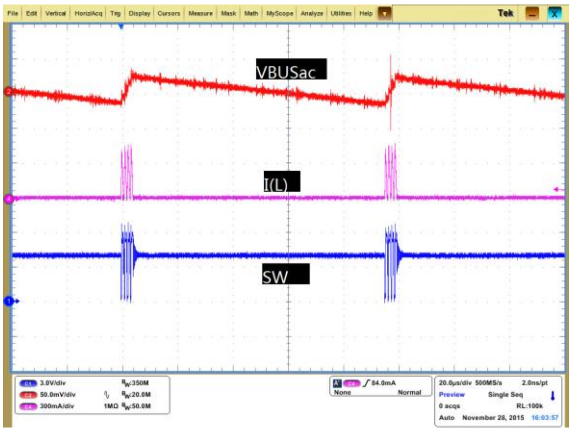


Figure 24. Boost PFM Waveform

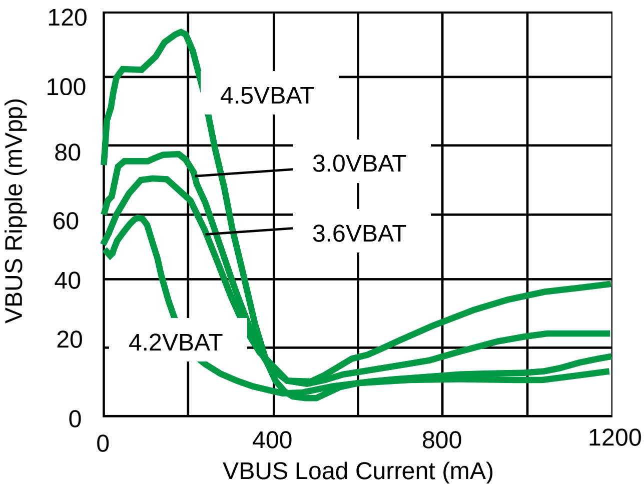


Figure 25. Output Ripple vs. VBAT

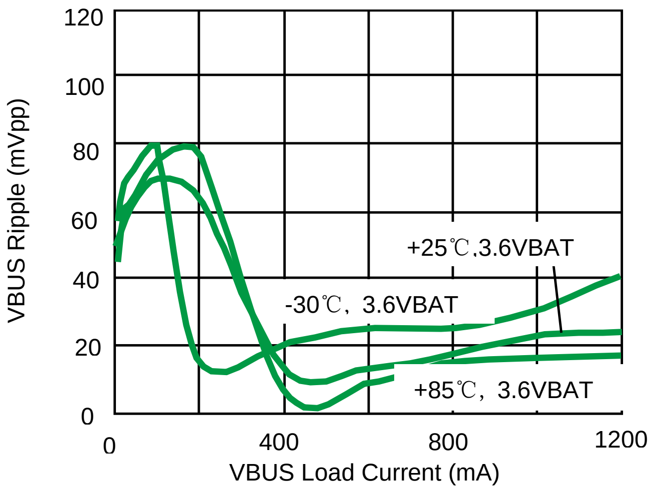


Figure 26. Output Ripple vs. Temperature

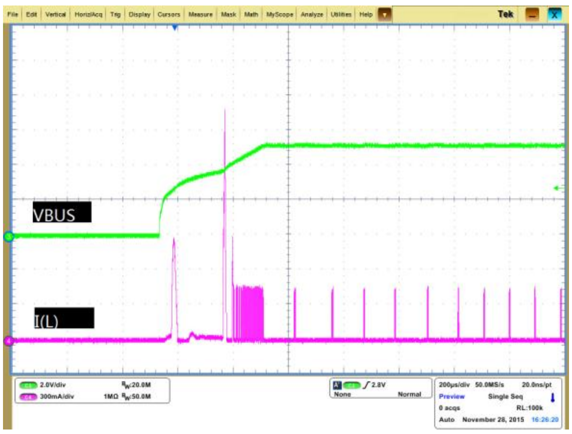


Figure 27.Startup, 3.6VBAT,44Ω Load, Additional 10μF, X5R Across VBUS

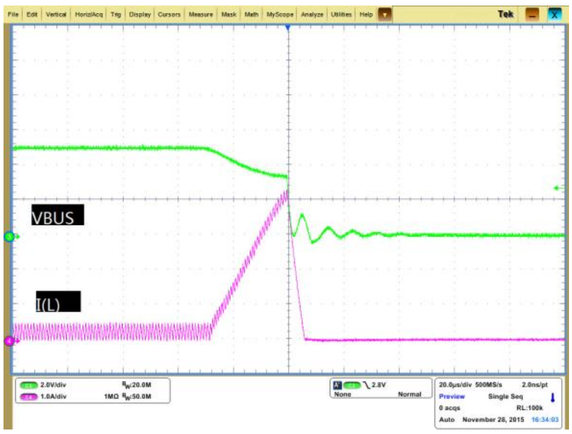


Figure 28. VBUS Fault Response, 3.6VBAT

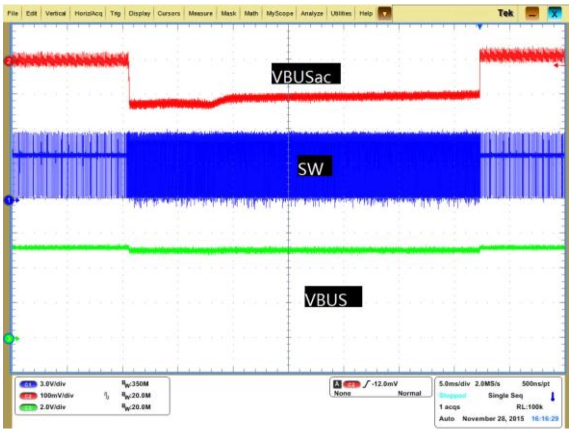


Figure 29. Load Transient, 1-150-1mA, t_R=t_F=100ns

Circuit Description/ Overview

When charging batteries with a current-limited input source, such as USB, a switching charger's high efficiency over a wide range of output voltages minimizes charging time.

PB15302 combines a highly integrated synchronous buck regulator for charging with a synchronous boost regulator, which can supply 5V to USB On-The-Go (OTG) peripherals. The regulator employs synchronous rectification for both the charger and boost regulators to maintain high efficiency over a wide range of battery voltages and charge states.

The PB15302 has three operating modes:

1. Charge Mode (VBUS is valid.):

   Charge a single-cell Li-ion or Li-polymer battery.

2. Boost Mode:

   Provide 5V power to USB-OTG with an integrated synchronous rectification boost regulator using the battery as input.

3. Standby mode (VBUS is not valid.)

   Current flow from VBUS to the battery or from the battery to VBUS is blocked.

   1) If HZ_MODE=0, boost can be turned on thru I2C.

   2) If HZ_MODE=1, boost is always off.

Note: Default settings are denoted by bold typeface.

Charge Mode

In Charge Mode, PB15302 employs four regulation loops:

1. Input Current: Limits the amount of current drawn from VBUS. This current is sensed internally and can be programmed through the I^2C interface.

2. Charging Current: Limits the maximum charging current. This current is sensed using an external R_{SENSE} resistor.

3. Charge Voltage: The regulator is restricted from exceeding this voltage. As the internal battery voltage rises, the battery's internal impedance and R_{SENSE} work in conjunction with the charge voltage regulation to decrease the amount of current flowing to the battery. Battery charging is completed when the charging current drops below the I_{TERM} threshold.

4. Input Voltage: PB15302 employ an additional loop to limit the amount of drop on VBUS to a programmable voltage (V_{SP}) to accommodate "special chargers" that limit current to a lower current than might be available from a "normal" USB wall charger.

Battery Charging Curve

If the battery voltage is below V_{SHORT}, a linear current source pre-charges the battery until V_{BAT} reaches V_{SHORT}. The PWM charging circuit is then started and the battery is charged with a constant current if sufficient input power is available. The current slew rate is limited to prevent overshoot.

The PB15302 is designed to work with a current-limited input source at VBUS. During the current regulation phase of charging, I_{INLIM} or the programmed charging current limits the amount of current available to charge the battery and power the system. The effect of I_{INLIM} on I_{CHARGE} can be seen in Figure 31.

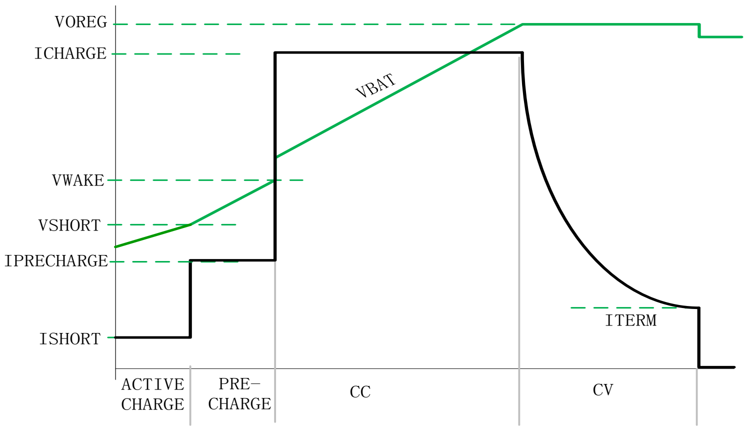


Figure 30. Charge Curve, I_{CHARGE} Not Limited by I_{INLIM}

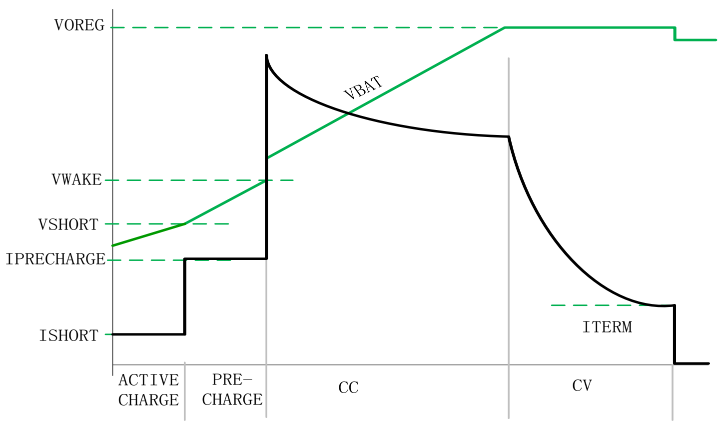


Figure 31. Charge Curve, I_{INLIM} Limits I_{CHARGE}

Assuming that V_{OREG} is programmed to the cell's fully charged "float" voltage, the current that the battery accepts with the PWM regulator limiting its output (sensed at VBAT) to V_{OREG} declines, and the charger enters the voltage regulation phase of charging. When the current declines to the programmed I_{TERM} value, the charge cycle is complete. Charge current termination can be disabled by resetting the TE bit (REG1[3]).

The charger output or "float" voltage can be programmed by the OREG bits from 4.1V to 4.4V as shown in Table 1.

Table 1. OREG Bits (OREG[7:2]) vs. Charger V_{OUT} (V_{OREG}) Float Voltage

Decimal	Hex	VOREG
0-1	00-01	4.10
2-35	02-23	4.20
36-44	24-2C	4.35
45-62	2D-3E	4.40

The following charging parameters can be programmed by the host through I^2C:

Table 2. Programmable Charging Parameters

Parameter	Name	Register
Output Voltage Regulation	V_{OREG}	REG2[7:2]
Battery Charging Current Limit	I_{OCHRG}	REG4[6:4]
Input Current Limit	I_{INLIM}	REG1[7:6]
Charge Termination Limit	I_{TERM}	REG4[2:0]
Weak Battery Voltage	V_{LOWV}	Reserved.

A new charge cycle begins when one of the following occurs:

- The battery voltage falls below V_{OREG}-V_{RCH}

Charge Current Limit ($I_{OCHARGE}$) & Termination Current Limit

Table 3. IOCHARGE (REG4 [6:4]) Current as Function of IOCHARGE Bits and RSENSE Resistor Values

DEC	BIN	HEX	V_{RSENSE}(mV)	$I_{OCHARGE}$(mA)	
				68mΩ	56mΩ
0	000	00	32.8	482	586
1	001	01	39.3	578	702
2	010	02	52.4	771	936
3	011	03	59.0	867	1054
4	100	04	72.1	1060	1288
5	101	05	78.7	1156	1405
6	110	06	91.8	1349	1639
7	111	07	98.3	1446	1755

Table 4. Terminated (REG4 [2:0]) Current as Function of ITERM Bits and RSENSE Resistor Values

DEC	BIN	HEX	V_{RSENSE}(mV)	I_{TERM}(mA)	
				68mΩ	56mΩ
0	000	00	2.5	36	45
1	001	01	3.8	55	68
2	010	02	5.0	73	89
3	011	03	6.3	91	113
4	100	04	7.5	110	134
5	101	05	8.8	128	157
6	110	06	10.0	147	179
7	111	07	11.3	165	202

Current charge termination is enabled when TE (REG1[3])=1. When charging current falls below I_{TERM}, PWM charging stops. If the charging source is still connected, STAT changes to CHARGE DONE (10).

PWM Controller in Charge Mode

The IC uses a current-mode PWM controller to regulate the output voltage and battery charge currents.

Safety Timer

The charger has a time out function for wake-up charge and normal charge. For wake-up charge the internal timer is set to typically 90 minutes. After 90 minutes of charging, if Vbat is still lower than 3.1V (typical), the charger is turned OFF and will not resume operation.

For normal charging the timer is set to 12 hours.

If the charger is still operating after typical 12 hours it will be turned OFF and will resume operating only if the condition (VOREG-VBAT) >100mV is met.

The 90-min and 12-hour timer can be reset by plugging out/in the adapter.

PB15302 also has a 32s-timer for watch-dog function which is only for OTG mode. If it does not receive any read/write command during 32s, it will be reset to default parameters and quit OTG mode.

VBUS POR / Non-Compliant Charger Rejection

When VBUS is inserted, VBUS must remain above $V_{IN(MIN)1}$ and below $VBUS_{OVP}$ for t_{VBUS_VALID} (25ms) before the IC initiates charging. The VBUS validation sequence always occurs before charging is initiated or re-initiated (for example, after a VBUS OVP fault or a V_{RCH} recharge initiation).

t_{VBUS_VALID} ensures that unfiltered 50/60Hz chargers and other non-compliant chargers are rejected.

Input Current Limiting

To minimize charging time without overloading VBUS current limitations, the IC's input current limit can be programmed by the I_{INLIM} bits (REG1[7:6]).

Table 5. Input Current Limit

I_{INLIM} REG1[7:6]	Input Current Limit
00	150mA
01	500mA
10	800mA
11	No Limit

Special Charger

The PB15302 have additional functionality to limit input current in case a current-limited “special charger” is supplying VBUS.

The PB15302 slowly increases the charging current until either:

I_{INLIM} or $I_{OCHARGE}$ is reached or $V_{BUS}=V_{SP}$

If V_{BUS} collapses to V_{SP} when the current is ramping up, the PB15302 charge with an input current that keeps $V_{BUS}=V_{SP}$.

Table 6. Input Voltage Limit

V_{SP} REG5[2:0]	Input Voltage Limit (V)
000	4.214
001	4.29
010	4.366
011	4.442
100	4.52(Default)
101	4.59
110	4.67
111	4.8

Thermal Protection

If the temperature increases beyond $T_{SHUTDOWN}$; charging is suspended, the FAULT bits are set to 101.

Note that as power dissipation increases, the effective θ_{JA} decreases due to the larger difference between the die temperature and its ambient.

Charge Mode Input Supply Protection

Input Supply Low-Voltage Detection

The IC continuously monitors VBUS during charging. If V_{BUS} falls below $V_{IN(MIN)}$, the IC terminates charging.

Input Over-Voltage Detection

When the VBUS exceeds $VBUS_{OVP}$, the IC suspends charging

When VBUS falls about 150mV below $VBUS_{OVP}$, the fault is cleared and charging resumes after VBUS is revalidated (see VBUS POR / Non-Compliant Charger Rejection).

Charge Mode Battery Detection & Protection

VBAT Over-Voltage Protection

The OREG voltage regulation loop prevents VBAT from overshooting the OREG voltage by more than 50mV when the battery is removed. When the PWM charger runs with no battery, the TE bit is not set and a battery is inserted that is charged to a voltage higher than V_{OREG}; PWM pulses stop.

System Operation with No Battery

The PB15302 continue charging after V_{BUS} POR with the default parameters, regulating the V_{BAT} line to 4.2V until the host processor issues commands. In this way, the PB15302 can start the system without a battery.

Using following sequence is suggested:

1. When VBUS is plugged in, I_{INLIM} is set to 500mA until the system processor powers up and can set parameters through I^2C.
2. Program the Safety Register.
3. Set I_{INLIM} to 11 (no limit).
4. Set OREG to the desired value (typically 4.2V).
5. Set I_{INLIM} to 500mA if a USB source is connected.

During the initial system startup, while the charger IC is being programmed, the system current is limited to 500mA before

Charger Status

The STAT pin is for test purpose, the IC provides the charging status in REG0[5:4].

Operational Mode Control

OPA_MODE (REG1[0]) and the HZ_MODE (REG1[1]) bits in conjunction with the DISABLE pin define the operational mode of the charger.

Table 7. Operation Mode Control

HZ_ MODE	OPA_MODE	DISABLE	Operation Mode
X	0	0	Charge
X	X	1	Charger disabled
0	1	X	Boost
1	X	X	High Impedance

The IC resets the OPA_MODE bit whenever the boost is deactivated, whether due to a fault or being disabled by setting the HZ_MODE bit. <u>Setting HZ_MODE=1 through I^2C won't disable charger but only disable boost function.</u>

Boost PWM Control

The IC uses a minimum on-time and computed minimum off-time to regulate VBUS. The regulator achieves excellent transient response by employing current-mode modulation. This technique causes the regulator to exhibit a load line. During PWM Mode, the output voltage drops slightly as the input current rises. With a constant V_{BAT}, this appears as a constant output resistance.

PFM Mode

If V_{BUS} > $VREF_{BOOST}$ (nominally 5.15V) when the minimum off-time has ended, the regulator enters PFM Mode. Boost pulses are inhibited until V_{BUS} < $VREF_{BOOST}$. The minimum on-time is increased to enable the output to pump up sufficiently with each PFM boost pulse. Therefore the regulator behaves like a constant on-time regulator, with the bottom of its output voltage ripple at 5.15V in PFM Mode.

Startup

When the boost regulator is shut down, current flow is prevented from V_{BAT} to V_{BUS}, as well as reverse flow from V_{BUS} to V_{BAT}.

SS State

This IC has built-in soft start function to prevent the IC being out of control. The reference voltage is slightly raised to the normal voltage within about 50us. In SS state, peak current is limited as 1.5x of that in normal condition. When SS is done, the current limit is set to 100%.

BST State

This is the normal operating mode of the regulator. The regulator uses a minimum t_{OFF}-minimum t_{ON} modulation scheme. The minimum t_{OFF} is proportional to $\frac{V_{IN}}{V_{OUT}}$ Which keeps the regulator's switching frequency reasonably constant in CCM. $t_{ON(MIN)}$ is proportional to VBAT and is a higher value if the inductor current reached 0 before $t_{OFF(MIN)}$ in the prior cycle.

To ensure the VBUS does not pump significantly above the regulation point, the boost switch remains off as long as FB > V_{REF}.

Boost Faults

If a BOOST fault occurs:

1. The STAT pin pulses.
2. OPA_MODE bit is reset.
3. The power stage is in High-Impedance Mode.

I²C Interface

The PB15302's serial interface is compatible with Standard, Fast, Fast Plus, and High-Speed Mode I²C-Bus® specifications. The PB15302's SCL line is an input and its SDA line is a bi-directional open-drain output; it can only pull down the bus when active. The SDA line only pulls LOW during data reads and when signaling ACK. All data is shifted in MSB (bit 7) first.

Slave Address

Table 8. I²C Slave Address Byte

Part Types	7	6	5	4	3	2	1	0
PB15302	1	1	0	1	0	1	0	R/$\overline{W}$

In hex notation, the slave address assumes a 0 LSB. The hex slave address for the PB15302 is D4H.

Bus Timing

As shown in Figure 32, data is normally transferred when SCL is LOW. Data is clocked in on the rising edge of SCL. Typically, data transitions shortly at or after the falling edge of SCL to allow ample time for the data to set up before the next SCL rising edge.

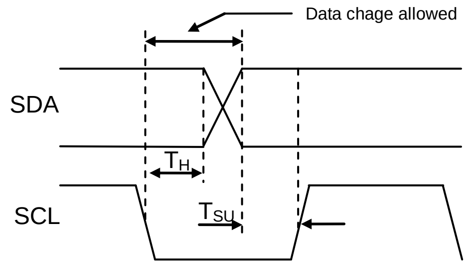


Figure 32. Data Transfer Timing

Each bus transaction begins and ends with SDA and SCL HIGH. A transaction begins with a START condition, which is defined as SDA transitioning from 1 to 0 with SCL HIGH, as shown in Figure 33.

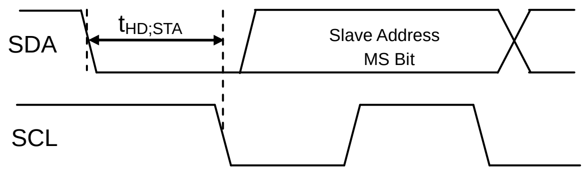


Figure 33. Start Bit

A transaction ends with a STOP condition, which is defined as SDA transitioning from 0 to 1 with SCL HIGH, as shown in Figure 34.

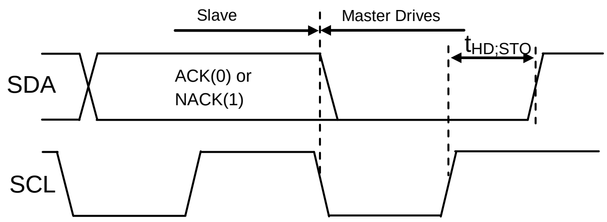


Figure 34. Stop Bit

During a read from the PB15302 (Figure 37), the master issues a Repeated Start after sending the register address and before resending the slave address. The Repeated Start is a 1-to-0 transition on SDA while SCL is HIGH, as shown in Figure 35.

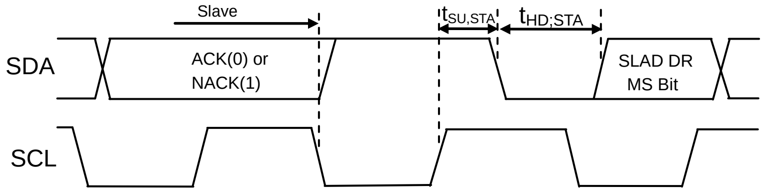


Figure 35. Repeated Start Timing

Read and Write Transactions

The figures below outline the sequences for data read and write. Bus control is signified by the shading of the packet, defined as [Master Drives Bus] and [Slave Drives Bus]

All addresses and data are MSB first.

Table 9. Bit Definitions for Figure 36, Figure 37

Symbol	Definition
S	START, see Figure 33
A	ACK. The slave drives SDA to 0 to acknowledge the preceding packet.
$\overline{A}$	NACK. The slave sends a 1 to NACK the preceding packet.
R	Repeated START, see Figure 35
P	STOP, see Figure 34

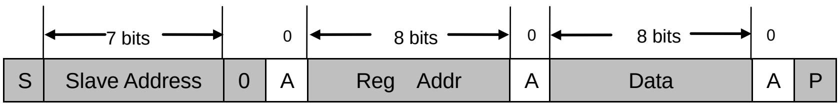


Figure 36. Write Transaction

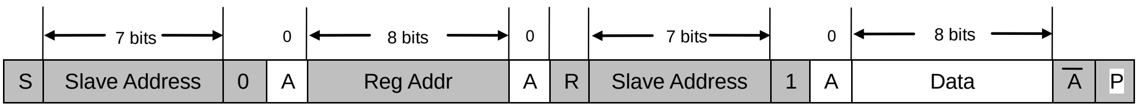


Figure 37. Read Transaction

Register Descriptions

Table 10. I²C Register Address

IC	Register		Address Bits							
	Name	REG#	7	6	5	4	3	2	1	0
PB15302	CONTROL0	0	0	0	0	0	0	0	0	0
	CONTROL1	1	0	0	0	0	0	0	0	1
	OREG	2	0	0	0	0	0	0	1	0
	IC_INFO	3	0	0	0	0	0	0	1	1
	IBAT	4	0	0	0	0	0	1	0	0
	SP_CHARGER	5	0	0	0	0	0	1	0	1
	SAFETY	6	0	0	0	0	0	1	1	0
	SPR	51	1	0	0	1	0	0	0	1
	TEST	10	0	0	0	1	0	0	0	0

Table 11. Register Bit Definitions

This table defines the operation of each register bit for all IC versions. Default values are in bold text.

Bit	Name	Value	Type	Description
CONTROL0				**Register Address:00 Default Value=X1XX 0XXX**
7:6	-	-	-	Reserved. [1]
5:4	STAT	00	R	Ready
		01		Charge in progress
		10		Charge done
		11		Fault
3	BOOST	0	R	IC is not in Boost Mode
		1		IC is in Boost Mode
2:0	-		R	

Note[1]: Any I2C operations can be used to reset 32s timer. If the 5415E is in OTG mode and does not receive any read/write command during 32s, it will be reset to default parameters and quit OTG mode.

<table>
<tr><th>Bit</th><th>Name</th><th>Value</th><th>Type</th><th colspan="2">Description</th></tr>
<tr><td colspan="4">CONTROL1</td><td>Register Address:01</td><td>Default Value=0111 0000(70H)</td></tr>
<tr><td rowspan="6">7:6</td><td rowspan="6">I_{INLIM}</td><td rowspan="6"></td><td rowspan="6">R/W</td><td colspan="2">Input current limit, see Table 5</td></tr>
<tr><td>REG01[7:6]
BIN</td><td>Input Current Limit</td></tr>
<tr><td>00</td><td>150mA</td></tr>
<tr><td>01</td><td>500mA</td></tr>
<tr><td>10</td><td>800mA</td></tr>
<tr><td>11</td><td>Unlimited</td></tr>
<tr><td>5:4</td><td>VLOWV</td><td></td><td>R/W</td><td colspan="2">Reserved.</td></tr>
<tr><td rowspan="2">3</td><td rowspan="2">TE</td><td>0</td><td rowspan="2">R/W</td><td colspan="2">Disable charge current termination</td></tr>
<tr><td>1</td><td colspan="2">Enable charge current termination</td></tr>
<tr><td rowspan="2">2</td><td rowspan="2">$\overline{CE}$</td><td>0</td><td rowspan="2">R/W</td><td colspan="2">Enable charge;</td></tr>
<tr><td>1</td><td colspan="2">Disable charge;</td></tr>
<tr><td rowspan="2">1</td><td rowspan="2">HZ_MODE</td><td>0</td><td rowspan="2">R/W</td><td colspan="2">Not High-Impedance Mode</td></tr>
<tr><td>1</td><td colspan="2">High-Impedance Mode</td></tr>
<tr><td rowspan="2">0</td><td rowspan="2">OPA_MODE</td><td>0</td><td rowspan="2">R/W</td><td colspan="2">Charge Mode</td></tr>
<tr><td>1</td><td colspan="2">Boost Mode</td></tr>
<tr><td colspan="4">OREG</td><td>Register Address:02</td><td>Default Value=0000 0000</td></tr>
<tr><td rowspan="6">7:2</td><td rowspan="6">OREG</td><td rowspan="6"></td><td rowspan="6">R/W</td><td colspan="2">Charger output “float” voltage; programmable from 4.2 to 4.4V increments; defaults to 000000 (4.1V), see Table 1</td></tr>
<tr><td>REG02[7:2]
BIN</td><td>VOREG</td></tr>
<tr><td>000000 - 000001</td><td>4.1V</td></tr>
<tr><td>000010 - 100011</td><td>4.2V</td></tr>
<tr><td>100100 - 101100</td><td>4.35V</td></tr>
<tr><td>101101 - 111110</td><td>4.4V</td></tr>
<tr><td>1:0</td><td>-</td><td>0</td><td>R/W</td><td colspan="2">-</td></tr>
<tr><td colspan="4">IC_INFO</td><td>Register Address: 03 or 3B</td><td>Default Value=1111 0XXX</td></tr>
<tr><td>7:5</td><td>Vendor Code</td><td>111</td><td>R</td><td colspan="2">Identifies Prisemi as the IC supplier</td></tr>
<tr><td>4:0</td><td>TN</td><td>10</td><td>R</td><td colspan="2">Product Tracking Number;</td></tr>
</table>

<table>
<tr><th colspan="2">IBAT</th><th colspan="2"></th><th>Register Address: 04   Default Value=1000 1001(89H)</th></tr>
<tr><td>7</td><td>RESET</td><td>1</td><td>W</td><td>Writing a 1 reset all charge parameters. Read returns 0</td></tr>
<tr><td>6:4</td><td>IOCHARGE</td><td>Table 3</td><td>R/W</td><td>Programs the maximum charge current, see Table 3
<table>
<tr><th rowspan="2">REG51[0]</th><th rowspan="2">REG04[6:4]
BIN</th><th rowspan="2">Vrsns(mV)</th><th colspan="2">Icharge (mA)</th></tr>
<tr><th>68mΩ</th><th>56mΩ</th></tr>
<tr><td rowspan="8">0</td><td>000</td><td>32.8</td><td>482</td><td>586</td></tr>
<tr><td>001</td><td>39.3</td><td>578</td><td>702</td></tr>
<tr><td>010</td><td>52.4</td><td>771</td><td>936</td></tr>
<tr><td>011</td><td>59</td><td>867</td><td>1054</td></tr>
<tr><td>100</td><td>72.1</td><td>1060</td><td>1288</td></tr>
<tr><td>101</td><td>78.7</td><td>1156</td><td>1405</td></tr>
<tr><td>110</td><td>91.8</td><td>1349</td><td>1639</td></tr>
<tr><td>111</td><td>98.3</td><td>1446</td><td>1755</td></tr>
<tr><td rowspan="8">1</td><td>000</td><td>26.7</td><td>392</td><td>477</td></tr>
<tr><td>001</td><td>33.3</td><td>490</td><td>595</td></tr>
<tr><td>010</td><td>40</td><td>588</td><td>714</td></tr>
<tr><td>011</td><td>46.7</td><td>686</td><td>834</td></tr>
<tr><td>100</td><td>53.3</td><td>784</td><td>952</td></tr>
<tr><td>101</td><td>60</td><td>882</td><td>1071</td></tr>
<tr><td>110</td><td>66.7</td><td>980</td><td>1191</td></tr>
<tr><td>111</td><td>86.7</td><td>1275</td><td>1548</td></tr>
</table></td></tr>
<tr><td>3</td><td>-</td><td>-</td><td>R</td><td>Reserved.</td></tr>
<tr><td>2:0</td><td>ITERM</td><td>Table 4</td><td>R/W</td><td>Programs the terminated charge-done current, see Table 4
<table>
<tr><th rowspan="2">REG04[2:0]
BIN</th><th colspan="3">ITERM (mA)</th></tr>
<tr><th>Vrsns</th><th>68mΩ</th><th>56mΩ</th></tr>
<tr><td>000</td><td>2.5</td><td>36</td><td>45</td></tr>
<tr><td>001</td><td>3.8</td><td>55</td><td>68</td></tr>
<tr><td>010</td><td>5.0</td><td>73</td><td>89</td></tr>
<tr><td>011</td><td>6.3</td><td>91</td><td>113</td></tr>
<tr><td>100</td><td>7.5</td><td>110</td><td>134</td></tr>
<tr><td>101</td><td>8.8</td><td>128</td><td>157</td></tr>
<tr><td>110</td><td>10.0</td><td>147</td><td>179</td></tr>
<tr><td>111</td><td>11.3</td><td>165</td><td>202</td></tr>
</table></td></tr>
</table>

<table>
<tr><th>Bit</th><th>Name</th><th>Value</th><th>Type</th><th colspan="2">Description</th></tr>
<tr><td colspan="4">SP_CHARGER</td><td>Register Address: 05</td><td>Default Value=001X X100</td></tr>
<tr><td>7</td><td>ADD20MV</td><td>0</td><td>R/W</td><td colspan="2">The OREG value will be increased 20mv if bit7 is set “1”; For example, 4.2 will be 4.22V if set ADD20MV=1;</td></tr>
<tr><td>6:5</td><td>Reserved</td><td>-</td><td>-</td><td colspan="2">Reserved</td></tr>
<tr><td rowspan="2">4</td><td rowspan="2">SP</td><td>0</td><td>R</td><td colspan="2">Special charger is not active (V_{BUS} is able to stay above V_{SP})</td></tr>
<tr><td>1</td><td></td><td colspan="2">Special charger has been detected and V_{BUS} is being regulated to</td></tr>
<tr><td>3</td><td>EN_LEVEL</td><td>0</td><td>R/W</td><td colspan="2">Reserved.</td></tr>
<tr><td rowspan="10">2:0</td><td rowspan="10">VSP</td><td rowspan="10">100</td><td rowspan="10">R/W</td><td colspan="2">Input voltage limit, see Table 6</td></tr>
<tr><td>REG05[2:0]
BIN</td><td>VSP (V)</td></tr>
<tr><td>000</td><td>4.214</td></tr>
<tr><td>001</td><td>4.29</td></tr>
<tr><td>010</td><td>4.366</td></tr>
<tr><td>011</td><td>4.442</td></tr>
<tr><td>100</td><td>4.52(default)</td></tr>
<tr><td>101</td><td>4.59</td></tr>
<tr><td>110</td><td>4.67</td></tr>
<tr><td>111</td><td>4.8</td></tr>
<tr><td colspan="4">SPR</td><td>Register Address: 51</td><td>Default Value=0000 0000 (00H)</td></tr>
<tr><td>1</td><td>FSE</td><td>0</td><td>R/W</td><td colspan="2">0: Choose PWM frequency 1.5Mhz;
1: Choose PWM frequency 2.0Mhz;</td></tr>
<tr><td>0</td><td>ICE</td><td>0</td><td>R/W</td><td colspan="2">Option for Charge current; see table 3</td></tr>
<tr><td colspan="4">TEST</td><td>Register Address: 10</td><td>Default Value=0000 0000 (00H)</td></tr>
<tr><td>2:0</td><td>TEST_STAT</td><td>000</td><td>R/W</td><td colspan="2">000: STAT output is low if VBUS is valid for charge, otherwise STAT is floating output;
111: STAT output is always floating;</td></tr>
</table>

PCB Layout Considerations

1. To obtain optimal performance, the power input capacitors, connected from input to GND, should be placed as close as possible to the pin. The output inductor should be placed close to the IC and the output capacitor connected between the inductor and GND of the IC. The intent is to minimize the current path loop area from the SW pin through the LC filter and back to the GND pin. To prevent high frequency oscillation problems, proper layout to minimize high frequency current path loop is critical. (See Figure 38.) The sense resistor should be adjacent to the junction of the inductor and output capacitor. Route the sense leads connected across the RSNS back to the IC, close to each other (minimize loop area) or on top of each other on adjacent layers (do not route the sense leads through a high-current path). (See Figure 39.)

2. Place all decoupling capacitors close to their respective IC pins and close to GND (do not place components such that routing interrupts power stage currents). All small control signals should be routed away from the high current paths.

3. The PCB should have a ground plane (return) connected directly to the return of all components through vias (two vias per capacitor for power-stage capacitors, two vias for the IC GND, one via per capacitor for small- signal components). A star ground design approach is typically used to keep circuit block currents isolated (high-power/low-power small-signal) which reduces noise-coupling and ground-bounce issues. A single ground plane for this design gives good results. With this small layout and a single ground plane, there is no ground-bounce issue, and having the components segregated minimizes coupling between signals.

4. The high-current charge paths into VBUS, PMID and from the SW pins must be sized appropriately for the maximum charge current in order to avoid voltage drops in these traces. The GND pins should be connected to the ground plane to return current through the internal low-side FET.

5. Place 22μF input capacitor as close to PMID pin and GND pin as possible to make high frequency current loop area as small as possible. Place 1μF input capacitor as close to VBUS pin and GND pin as possible to make high frequency current loop area as small as possible.

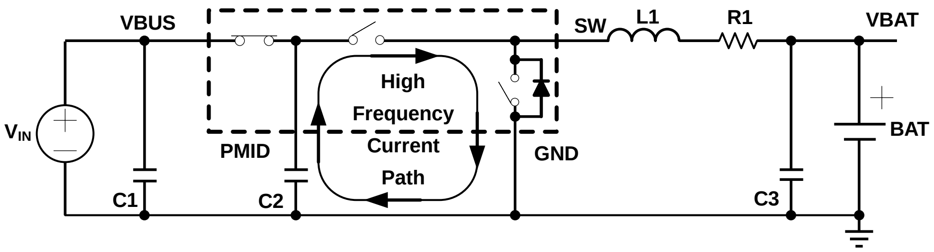


Figure 38. high frequency current path

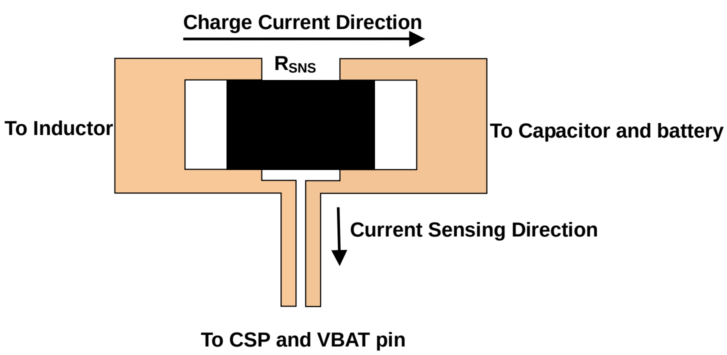
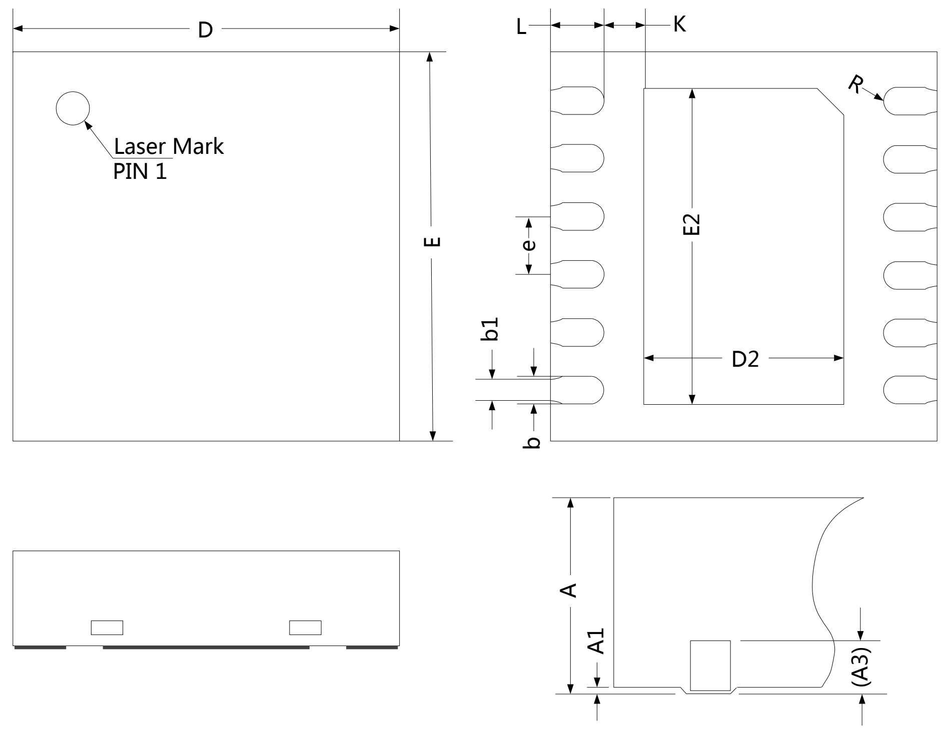


Figure 39. Sensing resistor PCB layout

Product dimension



SYMBOL	MIN (mm)	NOM (mm)	MAX (mm)
A	0.70	0.75	0.80
A1	0	0.02	0.05
A3	0.20REF		
b	0.15	0.20	0.25
b1	0.16REF		
D	2.90	3.00	3.10
E	2.90	3.00	3.10
D2	1.50	1.60	1.70
E2	2.40	2.50	2.60
e	0.35	0.45	0.55
K	0.20	--	--
L	0.30	0.40	0.50
R	0.13	--	--

Figure 41. DFN3.0mmx3.0mm, 12L, 0.45mm Pitch

Product-Specific Dimensions (mm)

Product	D	E	A	L
PB15302	3.0±0.1	3.0±0.1	0.75±0.05	0.40±0.10

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